

CGHV37400F

400 W, 3.5 - 3.7 GHz, 50-Ohm Input/Output Matched,
GaN HEMT for S-Band Radar Systems

Description

Cree's CGHV37400F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically with high efficiency, high gain and wide bandwidth capabilities, which makes the CGHV37400F ideal for 3.5 - 3.7 GHz S-Band radar amplifier applications. The transistor is matched to 50-ohms on the input and 50-ohms on the output. The CGHV37400F is based on Cree's high power density 50 V, 0.4 μm GaN on silicon carbide (SiC) foundry process. The transistor is supplied in a ceramic metal flange package, type 440217.



PN: CGHV37400F
Package Type: 440217

Typical Performance Over 3.5-3.7 GHz ($T_c = 25^\circ\text{C}$) of Demonstration Amplifier

Parameter	3.5 GHz	3.6 GHz	3.7 GHz	Units
Output Power	555	560	555	W
Gain	11.4	11.5	11.4	dB
Drain Efficiency	55	55	55	%

Note: Measured in the CGHV37400F-AMP application circuit, under 100 μs pulse width, 10% duty cycle, $P_{in} = 46\text{ dBm}$

Features

- 3.3 - 3.8 GHz Operation
- 525 W Typical Output Power
- 11.5 dB Power Gain
- 55% Typical Drain Efficiency
- 50 Ohm Internally Matched
- <0.3 dB Pulsed Amplitude Droop

Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Conditions
Pulse Width	PW	100	μs	
Duty Cycle	DC	10	%	
Drain-Source Voltage	V _{DSS}	150	Volts	25 °C
Gate-to-Source Voltage	V _{GS}	-10, +2	Volts	25 °C
Storage Temperature	T _{STG}	-65, +150	°C	
Operating Junction Temperature	T _J	225	°C	
Maximum Forward Gate Current	I _{GMAX}	80	mA	25 °C
Maximum Drain Current ¹	I _{DMAX}	24	A	25 °C
Soldering Temperature ²	T _S	245	°C	
Screw Torque	τ	40	in-oz	
Pulsed Thermal Resistance, Junction to Case	R _{θJC}	0.22	°C/W	100 μsec, 10%, 85 °C, P _{DISS} = 418 W
Case Operating Temperature	T _C	-40, +125	°C	

Notes:

¹ Current limit for long term, reliable operation² Refer to the Application Note on soldering at wolfspeed.com/rf/document-library**Electrical Characteristics**

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
DC Characteristics¹ (T_C = 25 °C)						
Gate Threshold Voltage	V _{GS(th)}	-3.8	-3.0	-2.3	V _{DC}	V _{DS} = 10 V, I _D = 83.6 mA
Gate Quiescent Voltage	V _{GS(Q)}	-	-2.7	-	V _{DC}	V _{DS} = 50 V, I _D = 1 A
Saturated Drain Current ²	I _{DS}	54.3	77.7	-	A	V _{DS} = 6.0 V, V _{GS} = 2.0 V
Drain-Source Breakdown Voltage	V _{BR}	125	-	-	V _{DC}	V _{GS} = -8 V, I _D = 83.6 mA
RF Characteristics³ (T_C = 25 °C, F₀ = 3.5 - 3.7 GHz unless otherwise noted)						
Output Power at 3.5 GHz	P _{OUT1}	400	525	-	W	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = 46 dBm
Output Power at 3.7 GHz	P _{OUT2}	400	525	-	W	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = 46 dBm
Drain Efficiency at 3.5 GHz	DE ₁	50	55	-	%	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = 46 dBm
Drain Efficiency at 3.7 GHz	DE ₂	50	55	-	%	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = 46 dBm
Small Signal Gain	S21	11.75	14	-	dB	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = -10 dBm
Input Return Loss	S11	-	-9	-4	dB	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = -10 dBm
Output Return Loss	S22	-	-6	-4	dB	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = -10 dBm
Amplitude Droop	D	-	-0.3	-	dB	V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = 46 dBm
Output Stress Match ⁴	VSWR	-	5:1	-	Ψ	No damage at all phase angles, V _{DD} = 50 V, I _{DQ} = 1000 mA, P _{IN} = 46 dBm Pulsed

Notes:

¹ Measured on wafer prior to packaging² Scaled from PCM data³ Measured in CGHV37400F-AMP. Pulse Width = 100 μs, Duty Cycle = 10%⁴ The device is not recommended for 5:1 VSWR applications below 3.3 GHz

Typical Performance

Figure 1. Typical Small Signal Gain and Return Losses vs Frequency
 $V_{DD} = 50\text{ V}$, $I_{DQ} = 1.0\text{ A}$

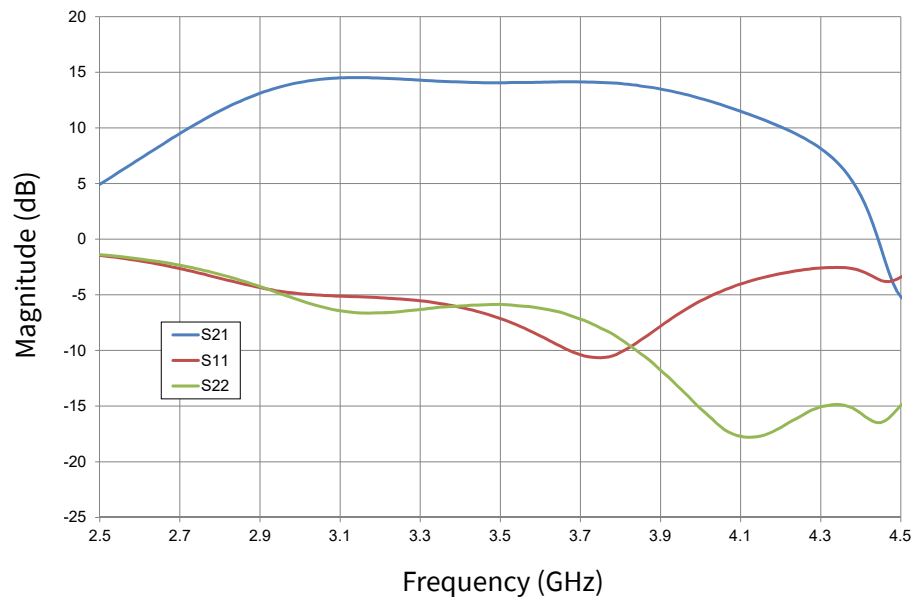
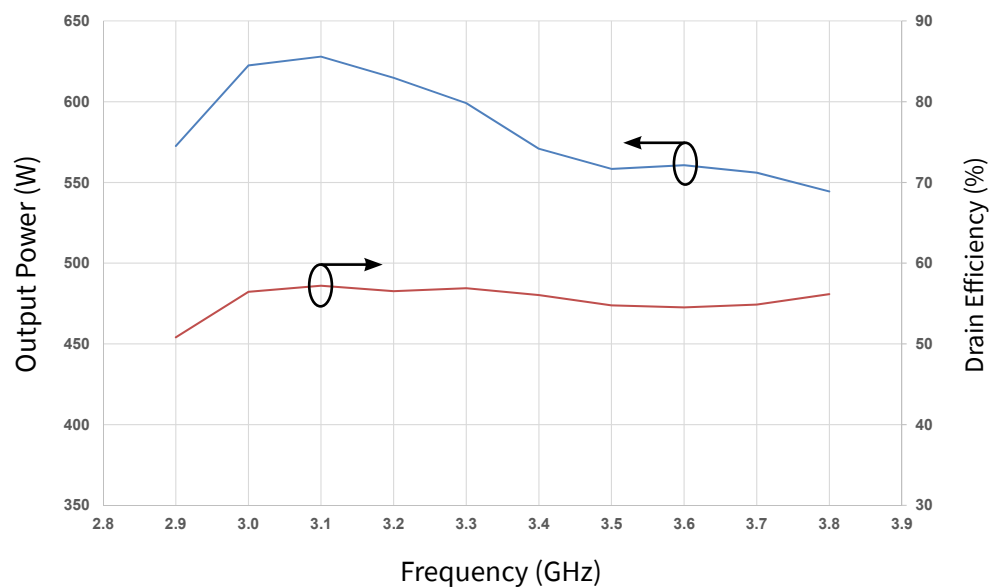


Figure 2. CGHV37400F Output Power and Drain Efficiency vs Frequency
 $V_{DD} = 50\text{ V}$, $I_{DQ} = 1.0\text{ A}$, $P_{IN} = 46\text{ dBm}$, Pulse Width = $100\mu\text{s}$, Duty Cycle = 10%, $T_{CASE} = 25^\circ\text{C}$



Typical Performance

Figure 3. Typical Output Power vs Input Power of the CGHV37400F
 $V_{DD} = 50 \text{ V}$, $I_{DQ} = 1.0 \text{ A}$, Pulse Width = $100 \mu\text{s}$, Duty Cycle = 10%, $T_{CASE} = 25^\circ \text{C}$

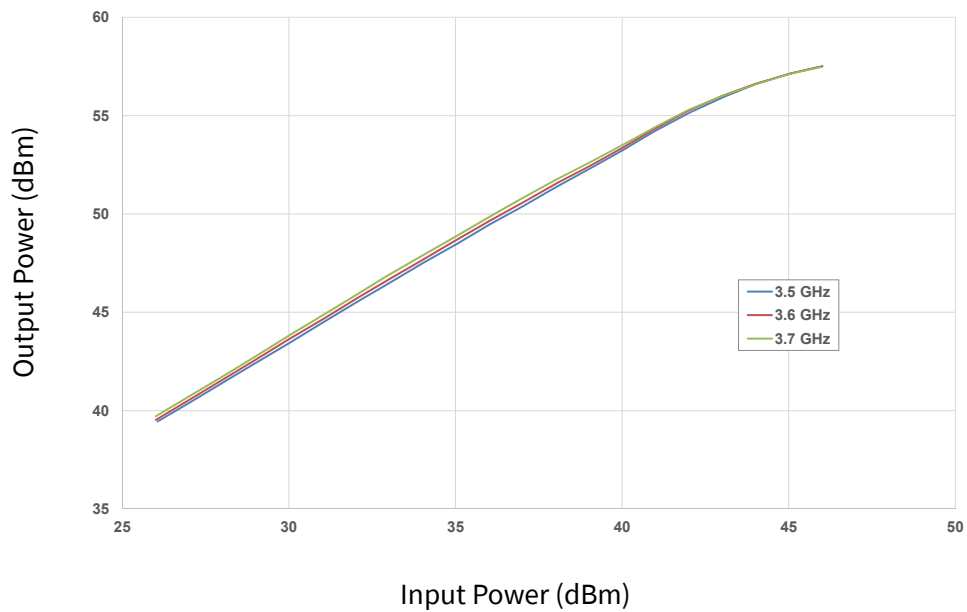
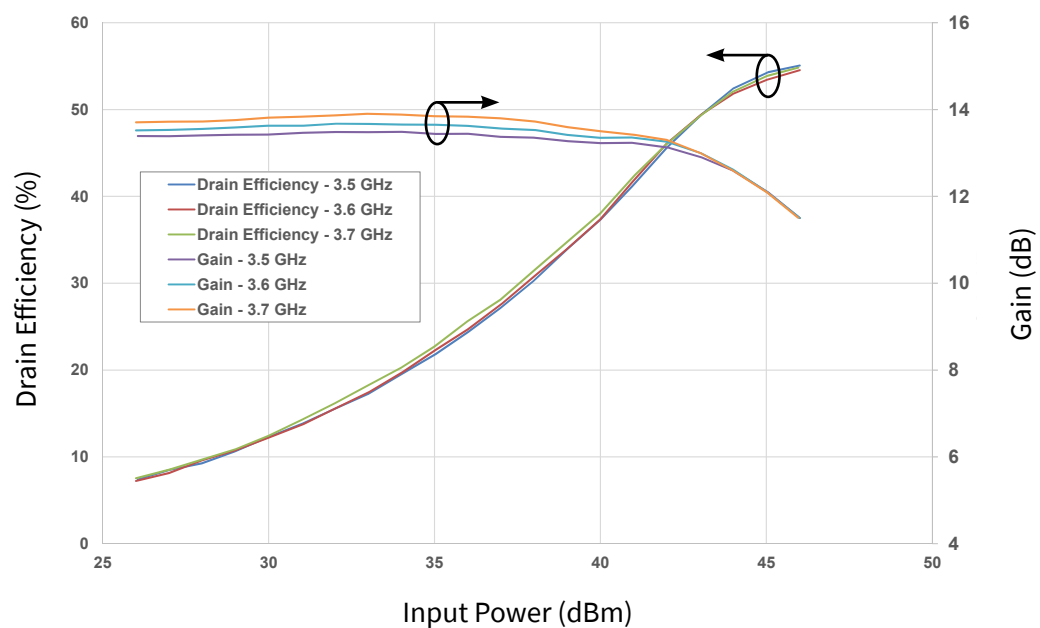


Figure 4. CGHV37400F Drain Efficiency and Gain vs Input Power
 $V_{DD} = 50 \text{ V}$, $I_{DQ} = 1.0 \text{ A}$, Pulse Width = $100 \mu\text{s}$, Duty Cycle = 10%, $T_{CASE} = 25^\circ \text{C}$



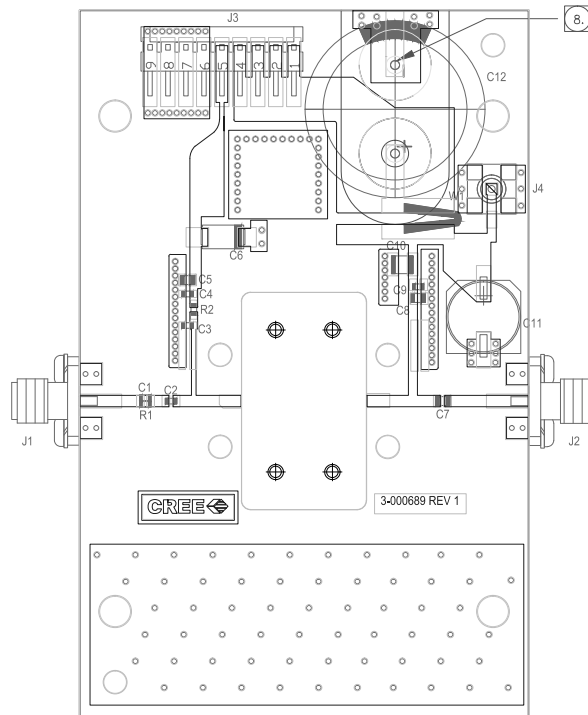
CGHV37400F-AMP Application Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 511, OHM, +/- 1%, 1/16W, 0603	1
R2	RES, 5.1, OHM, +/- 1%, 1/16W, 0603	1
C1	CAP, 6.8pF, +/-0.25%, 250V, 0603	1
C2, C7, C8	CAP, 10.0pF, +/-1%, 250V, 0805	3
C3	CAP, 10.0pF, +/-5%, 250V, 0603	1
C4, C9	CAP, 470pF, 5%, 100V, 0603, X	2
C5	CAP, 33000 pF, 0805, 100V, X7R	1
C6	CAP, 10uF 16V TANTALUM	1
C10	CAP, 1.0uF, 100V, 10%, X7R, 1210	1
C11	CAP, 33uF, 20%, G CASE	1
C12	CAP, 3300uF, +/-20%, 100V, ELECTROLYTIC	1
J1,J2	CONN, SMA, PANEL MOUNT JACK, FL	2
J3	HEADER, RT>PLZ, 0.1CEN LK 9POS	1
J4	CONNECTOR; SMB, Straight, JACK, SMD	1
W1	CABLE, 18 AWG, 4.2	1
-	PCB, RO4350, 2.5 X 4.0 X 0.030	1
Q1	CGHV37400F	1

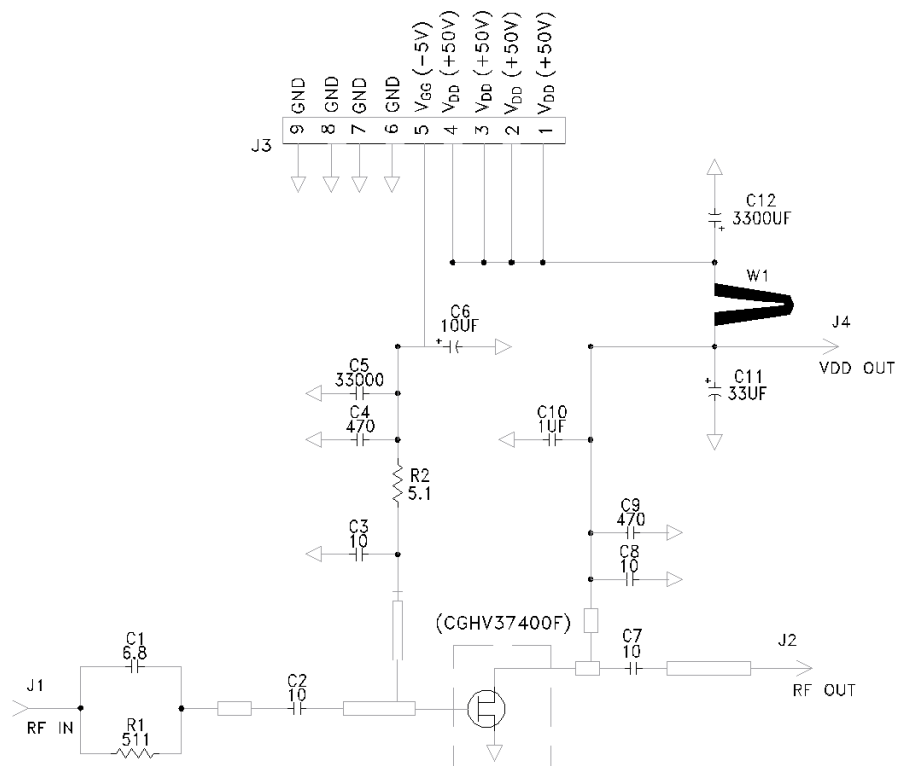
Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Test Methodology
Human Body Model	HBM	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	II (200 V < 500 V)	JEDEC JESD22 C101-C

CGHV37400F-AMP Application Circuit Outline



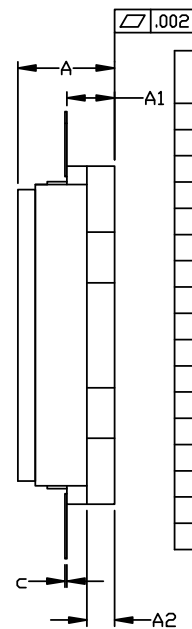
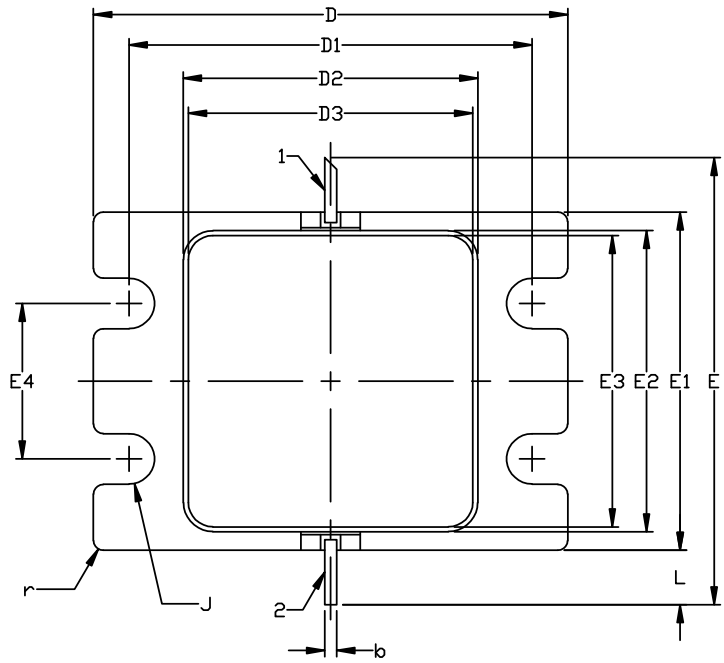
CGHV37400F-AMP Application Circuit Schematic



Product Dimensions CGHV37400F (Package Type — 440217)

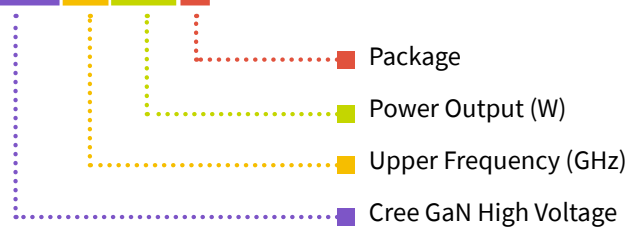
NOTES: (UNLESS OTHERWISE SPECIFIED)

- 1. INTERPRET DRAWING IN ACCORDANCE WITH ANSI Y14.5M-2009
- 2. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF .020 BEYOND EDGE OF LID
- 3. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF .008 IN ANY DIRECTION
- 4. ALL PLATED SURFACES ARE GOLD OVER NICKEL



DIM	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.188	0.198	4.78	5.03	
A1	0.088	0.100	2.24	2.54	2x
A2	0.049	0.061	1.24	1.55	
b	0.022	0.026	0.56	0.66	2x
c	0.002	0.006	0.05	0.15	
D	0.935	0.955	23.75	24.26	
D1	0.797	0.809	20.24	20.55	2x
D2	0.581	0.593	14.76	15.06	
D3	0.563	0.571	14.30	14.50	
E	0.906		23.01		REF
E1	0.679	0.691	17.25	17.55	
E2	0.604	0.616	15.34	15.65	
E3	0.586	0.594	14.88	15.09	
E4	0.309	0.321	7.85	8.15	2x
J	Ø0.097	Ø0.107	Ø2.46	Ø2.72	4x
L	0.090	0.130	2.29	3.30	2x
r	0.02 TYP		0.51 TYP		12x

Part Number System

CGHV37400F**Table 1.**

Parameter	Value	Units
Upper Frequency ¹	3.7	GHz
Power Output	400	W
Package	Flange	-

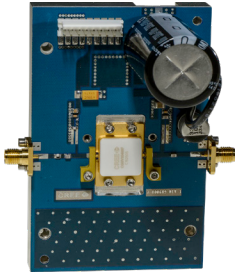
Note¹: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value

Table 2.

Character Code	Code Value
A	0
B	1
C	2
D	3
E	4
F	5
G	6
H	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGHV37400F	GaN HEMT	Each	
CGHV37400F-AMP	Test board with GaN HEMT installed	Each	

For more information, please contact:

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Notes

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